



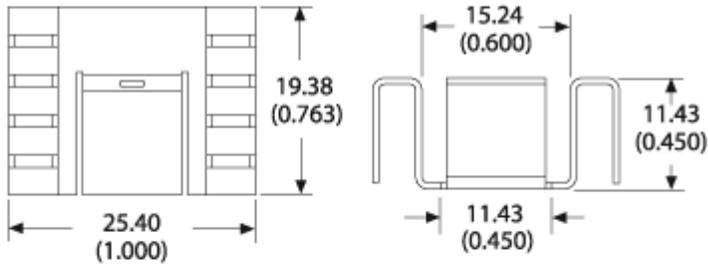
For use with Surface Mount packages

Part Number: 7109DG

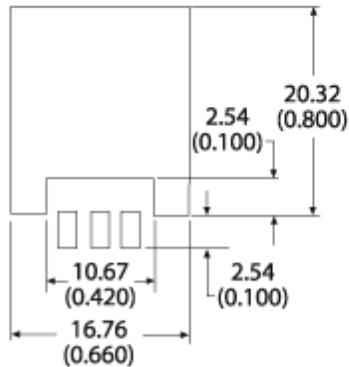
RoHS 
Compliant



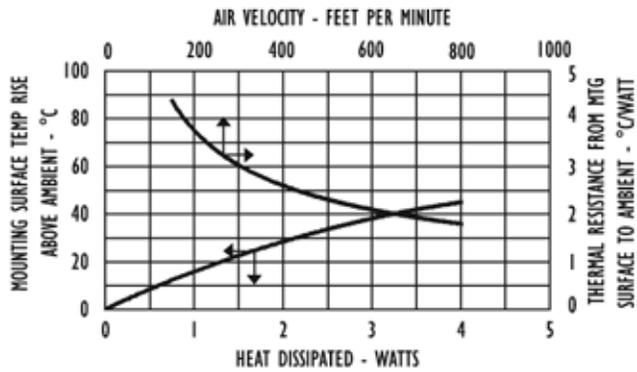
Mechanical Outline Drawing



Recommended copper pad size for heat sink and device mounting footprint



Thermal Curves



Thermal Resistance	11.00
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Thermal resistance value is based on a 75°C rise in natural convection

Product Information

Part #	Description	Finish
7109DG	Surface mount heat sink for D2 Pak (TO-263) package semiconductors	Matte Tin Plated

This non-electronic component is functionally unaffected by the normal soldering or reflow processes used for semiconductor circuits. The heat resistance time or heat resistance temperature is not applicable for the component.